

## **ABSTRACT OF THE DISCLOSURE**

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2           A heat dissipation method is provided for an electronic apparatus  
3 including a housing, a circuit board mounted in the housing, and a heatsink  
4 device mounted between and rested on the housing and the circuit board. The  
5 heatsink device includes a heatsink plate having a bottom face rested on a  
6 surface of the housing, and a heat conductive plate having a bottom face rested  
7 on a top face of the heatsink plate and a top face rested on a bottom face of the  
8 circuit board. Thus, the heatsink device dissipates the heat produced by the  
9 heat sources of the circuit board largely and rapidly, thereby enhancing the heat  
10 dissipation effect of the electronic apparatus.